

**To:** Sally Butts[sbutts@blm.gov]; Peter Mali[p mali@blm.gov]; Cindy Osorto[cosorto@blm.gov]  
**From:** Nelson, Britta  
**Sent:** 2017-02-27T12:13:27-05:00  
**Importance:** Normal  
**Subject:** Updated Monthly Hot Topic Snapshot for week of February 27  
**Received:** 2017-02-27T12:14:20-05:00  
[Monthly Hot Topic Snapshot for week of February 27.docx](#)  
[FY2017 Tracking Spreadsheet.xlsx](#)

The Monthly Hot Topic Snapshot has been updated. Please use the attached instead for our check in.

Thanks.

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (WO-410)  
Bureau of Land Management  
303.236.0539

On Mon, Feb 27, 2017 at 9:43 AM, Nelson, Britta <[bknelson@blm.gov](mailto:bknelson@blm.gov)> wrote:

Hi Sally, Peter, and Cindy - the Monthly Hot Topic Snapshot for the week of February 27 is attached for us to go over at today's check in. The tracking spreadsheet is also attached. Thanks.

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (WO-410)  
Bureau of Land Management  
303.236.0539



**NATIONAL  
CONSERVATION  
LANDS**

**March 2017  
Monthly Hot Topic Snapshot  
WO-410 RMP and EIS Review**  
Updated 02/27/17

**Nikki Moore**  
acting Assistant Director (WO-400)

**RMPS AND PROJECTS WITH ISSUES TO ELEVATE/DIRECTORS PRIORITIES**

- **DTS# 1401. NOA of the Boardman to Hemingway ROD. Oregon.**
  - **NOA has not reached WO400.** NOA not routed at Division level.
  - WO410 provided updated language for NSHT for the ROD to the Project Manager and WO210 (Jan 12, 2017).
- **Bering Sea-Western Interior preliminary range of alternatives. Alaska.**
  - WO410 submitted comments to WO210 for the wilderness, WSR, and NSHT programs (Nov. 2016).
  - **Update: 1) follow-up meeting scheduled with Alaska for March 1 for lands with wilderness characteristics. 2) a meeting is scheduled with Alaska for February 27 to discuss the Iditarod NHT and what interests and options there are, if any, as to BLM managing or regulating a ROW reservation for the Iditarod for the five townships/two Tentative Approvals that currently do not include a reservation.**
  - **Issues:**
    - Wilderness Program. **Update: Elevation paper submitted to AD for discussion w/SD.** An alternative protecting all or most of the lands with wilderness characteristics is not included in the range of alternatives. The "maximum protection" alternative only protects 2.5% of the planning area (which, minus a few tiny parcels, all contains wilderness characteristics).
    - Wild and Scenic Rivers. **Update: Alaska Recreation Lead, Tom Bickauskas, will follow up with Cathi Bailey.**
      - 1) Did not use the required range of alternatives for suitable WSRs (per manual 6400).
      - 2) All of the action alternatives have the 22 eligible rivers as not suitable. Yet Goal #1 is to effectively manage the ORVs identified during the eligibility inventory.
      - 3) Mitigation standard allows net loss to their designated Wild and Scenic River (Unalakleet).
    - National Trails. **Update: Iditarod NHT Manager (Kevin Keeler) and State NLCS Lead (Tom Bickauskas) spoke with Deb Salt on 02/22/17 and hope to complete the comment response by 02/24/17.**
      - 1) Iditarod NHT is not addressed in coal leasing decisions. Per 43 CFR 3400.2, coal leases shall not be issued on Federal Lands within the National System of Trails.
      - 2) Proposed disposal via state selection of the Rohn site, a site significant under the NTSA and NHPA.
- **Grand Staircase-Escalante National Monument administrative DRMP-A/DEIS WO Review. Utah.**
  - WO review of DRMP-A/DEIS from **January 30 to February 17. Comment period extended for WO410.**
  - Planning area a National Monument that contains wilderness characteristics, NSHT, WSR, wilderness, and WSA.
  - **Issues:** 1) More discussion is needed in plan alternatives on WSA non-impairment and grandfathered use requirements (40% of decision area is within WSAs). 2) Discussion of WSAs and designated Wilderness in the analysis should be separated (currently combined). 3) Discussion and analysis of impacts to Old Spanish NHT is needed.
- **Organ Mountains-Desert Peaks National Monument RMP Prep Plan. New Mexico.**
  - Prep plan review from February 13 through 24.

- **Browns Canyon National Monument RMP Prep Plan.** Colorado.
  - Prep plan review from February 13 through 24.
- **Appalachian Basin RMP Prep Plan.** Eastern States.
  - Prep plan review from February 27 through March 10.
- **Upper Snake, Challis, Salmon RMP Prep Plan.** Idaho.
  - Prep plan review from February 27 through March 10.
- **Verde Transmission ADEIS.** New Mexico.
  - **Issues:** Potential impacts to WSR and National Trails.
    - Proposed route crosses Rio Grande River. Eligible and suitable WSR streams in area including additional segments of the Rio Grande WSR.
    - Project would cross the Camino Real de Tierra Adentro NHT and Old Spanish NHT.
  - **Next milestone is review of ADEIS (TBD).** Any review is to be coordinated through New Mexico as amendment is not on WO210 priority list for WO review.
  - **Update:** Scoping Report is being prepared. Scoping indicates opposition to project.
- **Mancos Shale RMP-A NOI, Farmington, New Mexico.**
  - **Issues:** **Unknown** but WO410 is tracking because the RMP-A proposes to amend four decision types including lands with wilderness characteristics and will analyze potential impacts from oil and gas decisions to the Old Spanish NHT (RMP decisions for the NHT will not be made).
  - **As the RMP-A/EIS moves forward (alts development, impact analysis, etc.) WO410 will participate to ensure that the National Conservation Lands units are adequately considered.**
  - **Update:** draft alternatives will be completed this summer. Public release of the DRMP/DEIS is not anticipated until calendar year 2018. NMSO will coordinate with WO210 on WO review.

#### UPCOMING BRIEFINGS (NEXT 30 DAYS)

- **Lewistown DRMP/DEIS.** Montana.
  - **AD brief anticipated by mid-March.**
  - **No issues.** 202,730 acres contain wilderness characteristics. **100,410 acres (49%) would be managed to protect wilderness characteristics.** 30,000 acres would be managed to reduce impacts to wilderness characteristics (13,000 acres of ACECs and approximately 15,000-20,000 acres where actions are in place to protect GRSG). 70,000 acres would not be protected with underlying prescriptions including open to mineral material sales, non-energy leasables, cross-country mechanized travel, fluid minerals with minor constraints (CSU), and livestock; limited to designated routes yearlong; 400 acres of ERMA prescription (potentially); and mostly VRM III.
- **Carlsbad Field Office DRMP/DEIS.** New Mexico.
  - **Director's Brief was held on 09-27-16. Met with NMSO and WO210 to follow-up.**
  - **Follow up:** New Mexico is updating the briefing information related to lands with wilderness characteristics, including specifying acreage that the office will be protecting, maintaining, and not protecting; providing more detailed rationale for these decisions; clarifying that the entire FO was inventoried; and updating the maps to

make acreage protected/maintained/not protected more clear. Information related to WSR suitability will also be included either verbally or in the PowerPoint presentation.

- **Update: 02-03-17. Updated rationale provided by Carlsbad for WSR, under review.**
- AD Brief held 08-18-16. Pre-brief held 08-09-16.

- **Rio Puerco PRMP/FEIS.** New Mexico.

- **AD's Brief TBD.**
- **No outstanding 410 issues.** Rationale provided for lands with wilderness characteristics decisions (77% protected, 19% impacts minimized, 4% (1,663 acres) not protected.
  - The 1,663 acres is separated from other wilderness characteristics acres by natural geological barriers and has a separate access route. Area had interest from both the Wilderness Society and National Four Wheel Drive Association. New Mexico met with both groups and reached what everyone agreed was an equitable management approach. New Mexico received a "3 cape" award from the Wilderness Society for their efforts.

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Many thanks Ni ki and Bert al

Nelson Bita <b\_nelson@b-m.gov>  
Dec 5 (7 days ago)

Hi Fariba we wanted to let you know WORD provided a comment: nDTS

(B)(5) DPP

Cell 026

W. R. Nelson,  
H. R. Nelson and S.

(B)(5) DPP

The No Ice document is attached. Please let me know if additional information is needed.

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (NCL-632)

Cell G25

**Comment:** Mr Rita Nelson  
Hi Cezhi! It's a pleasure to hear from you. I'm glad to hear that you're doing well. I'm also glad to hear that you're working on your English. I'm sure you'll do great. I'll be here to help you whenever you need me. I'll be sure to let you know when I'm back in the States. I'll be sure to let you know when I'm back in the States. I'll be sure to let you know when I'm back in the States.

Does the language mean *is* provided to us?

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (NCL-632)  
Bureau of Land Management

Nov 29 (13 days ago)

no one in the

I don't quite remember the specifics of our request for the FRTs so I provide the following as a quick response:

The Proposed RM/Win ISG concurred in our view that the RDRs are eligible for potential designation as WD and Scenic Rivers, but the RDRs do not determine them to be suitable for designation as WD and Scenic Rivers, instead protecting them through a heretofore unprecedented

Comment: Britta Nelson.

May 18, 2015 - WOHSD has renamed the NDA for D -NCA.

Britta Nelson, M.P.A., Program Area Vice  
National Conservation Lands (NCL-432)  
Bureau of Land Management  
202 236-0529

— — — — — Fa un deal message — — — — —  
 Email: [burry.5.14@gmail.com](mailto:burry.5.14@gmail.com)

From: Butts, S. Ly <[butts@tin.goo](mailto:butts@tin.goo)>  
Date: Mon, 20 Jun 2005 12:07:00

Subje 1 Re: Feedback on OTS#1349-NDA of RGD or the Dominguez Escalante-National Consent on Air a Resource Management Plan Final Environmental Impact Statement

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da, aha a m'lii, con conghin go.

the total

Ija t earned Thanks for the good coordination on this

5a 4y

On Wed Nov 20 2016 at 5:30 PM, Nelson Brito <nbrito@unf.edu> wrote:  
In reply to the 20 and 28th posted by the anonymous to R. Brito.

Please let me know if there is any thing else needed before we name. Thanks

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (NCL-632)  
Bureau of Land Management

(B)(5) DPP

nick moore

Diwu Chen, Chief, National Conservation Land  
 Bureau of Land Management, Washington, DC  
 202 912 7624 (office)  
 202 288 9114 (cell)

On Tue, Nov 29, 2016 at 12:28 PM Neil on 811a <811a@bim-guo-w-cta>

Hi Nikk and Sa ly with the following feedback: surname of DTS# 1369/NOA of the ROD for the Domingue -Eca ante NICA is recommended I reviewed the package and found it consistent with our asset BP on the PRM/FE S at school I haven't sent the package to the p-ograms or review but can I you

(B)(5) DPP

The no ice documents have been shared with you. I haven't uploaded them into QTS yet so I can make sure to include your feedback and the program's feedback. Let me know how you would like to proceed.



Re: The National M.P.A. Program  
Re: The National M.P.A. Program (NPS-400)  
Bureau of Land Management  
202 216-5520

Call 527

Comment

(b)(5) DPP  
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Re: The National M.P.A. Program

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Re: The National M.P.A. Program

Call 528

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(B)(5) DPP

Pl. also let me know if you have any questions.

Call 046  
Comment: Britta Nelson  
03-13-17

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Print all in new window  
 Question on the NDA of FES for Proposed Land Exchange

Nelson R i ta <b nelson@b m gov>  
Atta hment 1 05 PM 2 minutes ago

to Timothy M. Ark, Sally Peier

Are there other acts of the National Center that on Lands or lands will increase the acts is it affected by the act on? Do you have feedback on the attached no fee package documents or should we move the package forward to Sally and Peter or someone?

Pl. ask if we know how we need to discuss. Thanks

Britta Nelson, M.P.A., Program Analyst  
National Conservation Lands (WFO-632)  
Bureau of Land Management  
202 236-0529

----- Forwarded message -----  
 From: <OTS@fcs.gov>

Subject: OTS Acquires No Use of Availability of First Environmental Impact Statement and Notice of Decision for Proposed Land Exchange between the Bureau of Land Management and the Nevada State Lands Department

Help and welcome to the DTS - you are all email star!

Year of ice (WO 450-NACS D VIS ON) has a task assigned

Please go into the Data Tracking System at the following URL Address: <https://dc.us.gov/dsp/preLogIn.do?field=6576> and review Document Control Number (DCN) BLMR001449

To move the document to the next office in the routing process, enter your e-mail name in destination for your checklist task and save the record.

Document Subject: Notice of Availability of Final Environmental Impact Statement and Notice of Decision on Proposed Land Exchange between the Bureau of Land Management and the Act on Required Action

Assigned By Office: WFO 250 LAND TENURE Unit: Law in Field

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Barling Sea View est	A.100	1000 no use of gas in kitchen range of extract fan provisions problem fixed gas safety test ok gas safe with no leaks gas safe with no																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																				

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Section	Sub-Section	Item	Document identifier	Document type	Document status	Document date	Document title	Document description	Document content	Document location	Document format	Document version
Section 1	Sub-Section 1	Item 1	Document identifier 1	Document type 1	Document status 1	Document date 1	Document title 1	Document description 1	Document content 1	Document location 1	Document format 1	Document version 1
Section 2	Sub-Section 2	Item 2	Document identifier 2	Document type 2	Document status 2	Document date 2	Document title 2	Document description 2	Document content 2	Document location 2	Document format 2	Document version 2
Section 3	Sub-Section 3	Item 3	Document identifier 3	Document type 3	Document status 3	Document date 3	Document title 3	Document description 3	Document content 3	Document location 3	Document format 3	Document version 3
Section 4	Sub-Section 4	Item 4	Document identifier 4	Document type 4	Document status 4	Document date 4	Document title 4	Document description 4	Document content 4	Document location 4	Document format 4	Document version 4

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Sharon Knowlton  
RIM Project Manager, Cheyenne State Office  
SIS21e owns one Road  
Cheyenne, Wyoming 82009  
307.775.6124 cel 305.572.6305  
fax 307.775.6202

So entry is not freedom from the storm, but peace within the storm.

[illegible]

Sharon Knowlton  
BIM Project Manager, Cheyenne State Office  
SIS Systems One Road  
Cheyenne, Wyoming 82009  
307.775.6124 cel 307.572.6100  
fax 307.775.6203

So entry is not freedom from the storm, but peace within the storm.

[illegible]







[illegible]

[illegible][illegible][illegible]

Cell: C14

Comment: 8/17/13 Nelson

8/24/13: S. review per lod began 06/20/14 and ended on 07/18/14. We discussed program comments provided on 06/20/14. Submit ted: o Tamara Gerth's and Renee S. rubin on 07/14/14. WSR comment: c submit ted on 07/15/14. NGH comments submit ted on 07/18/14.

Cell: A15  
Comment: Re Rita Nelson  
05-13-14  
Not on Consensus ion Lands, your review of the final data (RSD for TIME, ROW, and NGA package) is requested. Please provide feedback to me by May 20. Add additional comments in the comment box. Sharon's note below this cell is of three emails from Sharon I will forward.

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[illegible]



































2023									
Project Name	Project No.	Project Title	Project Status	Project Manager	Project Description	Project Location	Project Date	Project Notes	Project Contact
Project A	001	Project A Title	Project A Status	Project A Manager	Project A Description	Project A Location	Project A Date	Project A Notes	Project A Contact
Project B	002	Project B Title	Project B Status	Project B Manager	Project B Description	Project B Location	Project B Date	Project B Notes	Project B Contact
Project C	003	Project C Title	Project C Status	Project C Manager	Project C Description	Project C Location	Project C Date	Project C Notes	Project C Contact
Project D	004	Project D Title	Project D Status	Project D Manager	Project D Description	Project D Location	Project D Date	Project D Notes	Project D Contact
Project E	005	Project E Title	Project E Status	Project E Manager	Project E Description	Project E Location	Project E Date	Project E Notes	Project E Contact
Project F	006	Project F Title	Project F Status	Project F Manager	Project F Description	Project F Location	Project F Date	Project F Notes	Project F Contact
Project G	007	Project G Title	Project G Status	Project G Manager	Project G Description	Project G Location	Project G Date	Project G Notes	Project G Contact
Project H	008	Project H Title	Project H Status	Project H Manager	Project H Description	Project H Location	Project H Date	Project H Notes	Project H Contact
Project I	009	Project I Title	Project I Status	Project I Manager	Project I Description	Project I Location	Project I Date	Project I Notes	Project I Contact
Project J	010	Project J Title	Project J Status	Project J Manager	Project J Description	Project J Location	Project J Date	Project J Notes	Project J Contact
Project K	011	Project K Title	Project K Status	Project K Manager	Project K Description	Project K Location	Project K Date	Project K Notes	Project K Contact
Project L	012	Project L Title	Project L Status	Project L Manager	Project L Description	Project L Location	Project L Date	Project L Notes	Project L Contact
Project M	013	Project M Title	Project M Status	Project M Manager	Project M Description	Project M Location	Project M Date	Project M Notes	Project M Contact
Project N	014	Project N Title	Project N Status	Project N Manager	Project N Description	Project N Location	Project N Date	Project N Notes	Project N Contact
Project O	015	Project O Title	Project O Status	Project O Manager	Project O Description	Project O Location	Project O Date	Project O Notes	Project O Contact
Project P	016	Project P Title	Project P Status	Project P Manager	Project P Description	Project P Location	Project P Date	Project P Notes	Project P Contact
Project Q	017	Project Q Title	Project Q Status	Project Q Manager	Project Q Description	Project Q Location	Project Q Date	Project Q Notes	Project Q Contact
Project R	018	Project R Title	Project R Status	Project R Manager	Project R Description	Project R Location	Project R Date	Project R Notes	Project R Contact
Project S	019	Project S Title	Project S Status	Project S Manager	Project S Description	Project S Location	Project S Date	Project S Notes	Project S Contact
Project T	020	Project T Title	Project T Status	Project T Manager	Project T Description	Project T Location	Project T Date	Project T Notes	Project T Contact
Project U	021	Project U Title	Project U Status	Project U Manager	Project U Description	Project U Location	Project U Date	Project U Notes	Project U Contact
Project V	022	Project V Title	Project V Status	Project V Manager	Project V Description	Project V Location	Project V Date	Project V Notes	Project V Contact
Project W	023	Project W Title	Project W Status	Project W Manager	Project W Description	Project W Location	Project W Date	Project W Notes	Project W Contact
Project X	024	Project X Title	Project X Status	Project X Manager	Project X Description	Project X Location	Project X Date	Project X Notes	Project X Contact
Project Y	025	Project Y Title	Project Y Status	Project Y Manager	Project Y Description	Project Y Location	Project Y Date	Project Y Notes	Project Y Contact
Project Z	026	Project Z Title	Project Z Status	Project Z Manager	Project Z Description	Project Z Location	Project Z Date	Project Z Notes	Project Z Contact
Project AA	027	Project AA Title	Project AA Status	Project AA Manager	Project AA Description	Project AA Location	Project AA Date	Project AA Notes	Project AA Contact
Project AB	028	Project AB Title	Project AB Status	Project AB Manager	Project AB Description	Project AB Location	Project AB Date	Project AB Notes	Project AB Contact
Project AC	029	Project AC Title	Project AC Status	Project AC Manager	Project AC Description	Project AC Location	Project AC Date	Project AC Notes	Project AC Contact
Project AD	030	Project AD Title	Project AD Status	Project AD Manager	Project AD Description	Project AD Location	Project AD Date	Project AD Notes	Project AD Contact
Project AE	031	Project AE Title	Project AE Status	Project AE Manager	Project AE Description	Project AE Location	Project AE Date	Project AE Notes	Project AE Contact
Project AF	032	Project AF Title	Project AF Status	Project AF Manager	Project AF Description	Project AF Location	Project AF Date	Project AF Notes	Project AF Contact
Project AG	033	Project AG Title	Project AG Status	Project AG Manager	Project AG Description	Project AG Location	Project AG Date	Project AG Notes	Project AG Contact
Project AH	034	Project AH Title	Project AH Status	Project AH Manager	Project AH Description	Project AH Location	Project AH Date	Project AH Notes	Project AH Contact
Project AI	035	Project AI Title	Project AI Status	Project AI Manager	Project AI Description	Project AI Location	Project AI Date	Project AI Notes	Project AI Contact
Project AJ	036	Project AJ Title	Project AJ Status	Project AJ Manager	Project AJ Description	Project AJ Location	Project AJ Date	Project AJ Notes	Project AJ Contact
Project AK	037	Project AK Title	Project AK Status	Project AK Manager	Project AK Description	Project AK Location	Project AK Date	Project AK Notes	Project AK Contact
Project AL	038	Project AL Title	Project AL Status	Project AL Manager	Project AL Description	Project AL Location	Project AL Date	Project AL Notes	Project AL Contact
Project AM	039	Project AM Title	Project AM Status	Project AM Manager	Project AM Description	Project AM Location	Project AM Date	Project AM Notes	Project AM Contact
Project AN	040	Project AN Title	Project AN Status	Project AN Manager	Project AN Description	Project AN Location	Project AN Date	Project AN Notes	Project AN Contact
Project AO	041	Project AO Title	Project AO Status	Project AO Manager	Project AO Description	Project AO Location	Project AO Date	Project AO Notes	Project AO Contact
Project AP	042	Project AP Title	Project AP Status	Project AP Manager	Project AP Description	Project AP Location	Project AP Date	Project AP Notes	Project AP Contact
Project AQ	043	Project AQ Title	Project AQ Status	Project AQ Manager	Project AQ Description	Project AQ Location	Project AQ Date	Project AQ Notes	Project AQ Contact
Project AR	044	Project AR Title	Project AR Status	Project AR Manager	Project AR Description	Project AR Location	Project AR Date	Project AR Notes	Project AR Contact
Project AS	045	Project AS Title	Project AS Status	Project AS Manager	Project AS Description	Project AS Location	Project AS Date	Project AS Notes	Project AS Contact
Project AT	046	Project AT Title	Project AT Status	Project AT Manager	Project AT Description	Project AT Location	Project AT Date	Project AT Notes	Project AT Contact
Project AU	047	Project AU Title	Project AU Status	Project AU Manager	Project AU Description	Project AU Location	Project AU Date	Project AU Notes	Project AU Contact
Project AV	048	Project AV Title	Project AV Status	Project AV Manager	Project AV Description	Project AV Location	Project AV Date	Project AV Notes	Project AV Contact
Project AW	049	Project AW Title	Project AW Status	Project AW Manager	Project AW Description	Project AW Location	Project AW Date	Project AW Notes	Project AW Contact
Project AX	050	Project AX Title	Project AX Status	Project AX Manager	Project AX Description	Project AX Location	Project AX Date	Project AX Notes	Project AX Contact
Project AY	051	Project AY Title	Project AY Status	Project AY Manager	Project AY Description	Project AY Location	Project AY Date	Project AY Notes	Project AY Contact
Project AZ	052	Project AZ Title	Project AZ Status	Project AZ Manager	Project AZ Description	Project AZ Location	Project AZ Date	Project AZ Notes	Project AZ Contact
Project BA	053	Project BA Title	Project BA Status	Project BA Manager	Project BA Description	Project BA Location	Project BA Date	Project BA Notes	Project BA Contact
Project BB	054	Project BB Title	Project BB Status	Project BB Manager	Project BB Description	Project BB Location	Project BB Date	Project BB Notes	Project BB Contact
Project BC	055	Project BC Title	Project BC Status	Project BC Manager	Project BC Description	Project BC Location	Project BC Date	Project BC Notes	Project BC Contact
Project BD	056	Project BD Title	Project BD Status	Project BD Manager	Project BD Description	Project BD Location	Project BD Date	Project BD Notes	Project BD Contact
Project BE	057	Project BE Title	Project BE Status	Project BE Manager	Project BE Description	Project BE Location	Project BE Date	Project BE Notes	Project BE Contact
Project BF	058	Project BF Title	Project BF Status	Project BF Manager	Project BF Description	Project BF Location	Project BF Date	Project BF Notes	Project BF Contact
Project BG	059	Project BG Title	Project BG Status	Project BG Manager	Project BG Description	Project BG Location	Project BG Date	Project BG Notes	Project BG Contact
Project BH	060	Project BH Title	Project BH Status	Project BH Manager	Project BH Description	Project BH Location	Project BH Date	Project BH Notes	Project BH Contact
Project BI	061	Project BI Title	Project BI Status	Project BI Manager	Project BI Description	Project BI Location	Project BI Date	Project BI Notes	Project BI Contact
Project BJ	062	Project BJ Title	Project BJ Status	Project BJ Manager	Project BJ Description	Project BJ Location	Project BJ Date	Project BJ Notes	Project BJ Contact
Project BK	063	Project BK Title	Project BK Status	Project BK Manager	Project BK Description	Project BK Location	Project BK Date	Project BK Notes	Project BK Contact
Project BL	064	Project BL Title	Project BL Status	Project BL Manager	Project BL Description	Project BL Location	Project BL Date	Project BL Notes	Project BL Contact
Project BM	065	Project BM Title	Project BM Status	Project BM Manager	Project BM Description	Project BM Location	Project BM Date	Project BM Notes	Project BM Contact
Project BN	066	Project BN Title	Project BN Status	Project BN Manager	Project BN Description	Project BN Location	Project BN Date	Project BN Notes	Project BN Contact
Project BO	067	Project BO Title	Project BO Status	Project BO Manager	Project BO Description	Project BO Location	Project BO Date	Project BO Notes	Project BO Contact
Project BP	068	Project BP Title	Project BP Status	Project BP Manager	Project BP Description	Project BP Location	Project BP Date	Project BP Notes	Project BP Contact
Project BQ	069	Project BQ Title	Project BQ Status	Project BQ Manager	Project BQ Description	Project BQ Location	Project BQ Date	Project BQ Notes	Project BQ Contact
Project BR	070	Project BR Title	Project BR Status	Project BR Manager	Project BR Description	Project BR Location	Project BR Date	Project BR Notes	Project BR Contact
Project BS	071	Project BS Title	Project BS Status	Project BS Manager	Project BS Description	Project BS Location	Project BS Date	Project BS Notes	Project BS Contact
Project BT	072	Project BT Title	Project BT Status	Project BT Manager	Project BT Description	Project BT Location	Project BT Date	Project BT Notes	Project BT Contact
Project BU	073	Project BU Title	Project BU Status	Project BU Manager	Project BU Description	Project BU Location	Project BU Date	Project BU Notes	Project BU Contact
Project BV	074	Project BV Title	Project BV Status	Project BV Manager	Project BV Description	Project BV Location	Project BV Date	Project BV Notes	Project BV Contact
Project BW	075	Project BW Title	Project BW Status	Project BW Manager	Project BW Description	Project BW Location	Project BW Date	Project BW Notes	Project BW Contact
Project BX	076	Project BX Title	Project BX Status	Project BX Manager	Project BX Description	Project BX Location	Project BX Date	Project BX Notes	Project BX Contact
Project BY	077	Project BY Title	Project BY Status	Project BY Manager	Project BY Description	Project BY Location	Project BY Date	Project BY Notes	Project BY Contact
Project BZ	078	Project BZ Title	Project BZ Status	Project BZ Manager	Project BZ Description	Project BZ Location	Project BZ Date	Project BZ Notes	Project BZ Contact
Project CA	079	Project CA Title	Project CA Status	Project CA Manager	Project CA Description	Project CA Location	Project CA Date	Project CA Notes	Project CA Contact
Project CB	080	Project CB Title	Project CB Status	Project CB Manager	Project CB Description	Project CB Location	Project CB Date	Project CB Notes	Project CB Contact
Project CC	081	Project CC Title	Project CC Status	Project CC Manager	Project CC Description	Project CC Location	Project CC Date	Project CC Notes	Project CC Contact
Project CD	082	Project CD Title	Project CD Status	Project CD Manager	Project CD Description	Project CD Location	Project CD Date	Project CD Notes	Project CD Contact
Project CE	083	Project CE Title	Project CE Status	Project CE Manager	Project CE Description	Project CE Location	Project CE Date	Project CE Notes	Project CE Contact
Project CF	084	Project CF Title	Project CF Status	Project CF Manager	Project CF Description	Project CF Location	Project CF Date	Project CF Notes	Project CF Contact
Project CG	085	Project CG Title	Project CG Status	Project CG Manager	Project CG Description	Project CG Location	Project CG Date	Project CG Notes	Project CG Contact
Project CH	086	Project CH Title	Project CH Status	Project CH Manager	Project CH Description	Project CH Location	Project CH Date	Project CH Notes	Project CH Contact
Project CI	087	Project CI Title	Project CI Status	Project CI Manager	Project CI Description	Project CI Location	Project CI Date	Project CI Notes	Project CI Contact
Project CJ	088	Project CJ Title	Project CJ Status	Project CJ Manager	Project CJ Description	Project CJ Location	Project CJ Date	Project CJ Notes	Project CJ Contact
Project CK	089	Project CK Title	Project CK Status	Project CK Manager	Project CK Description	Project CK Location	Project CK Date	Project CK Notes	Project CK Contact
Project CL	090	Project CL Title	Project CL Status	Project CL Manager	Project CL Description	Project CL Location	Project CL Date	Project CL Notes	Project CL Contact
Project CM	091	Project CM Title	Project CM Status	Project CM Manager	Project CM Description	Project CM Location	Project CM Date	Project CM Notes	Project CM Contact
Project CN	092	Project CN Title	Project CN Status	Project CN Manager	Project CN Description	Project CN Location	Project CN Date	Project CN Notes	Project CN Contact
Project CO	093	Project CO Title	Project CO Status	Project CO Manager	Project CO Description	Project CO Location	Project CO Date	Project CO Notes	Project CO Contact
Project CP	094	Project CP Title	Project CP Status	Project CP Manager	Project CP Description	Project CP Location	Project CP Date	Project CP Notes	Project CP Contact
Project CQ	095	Project CQ Title	Project CQ Status	Project CQ Manager	Project CQ Description	Project CQ Location	Project CQ Date	Project CQ Notes	Project CQ Contact
Project CR	096	Project CR Title	Project CR Status	Project CR Manager	Project CR Description	Project CR Location	Project CR Date	Project CR Notes	Project CR Contact
Project CS	097	Project CS Title	Project CS Status	Project CS Manager	Project CS Description	Project CS Location	Project CS Date	Project CS Notes	Project CS Contact
Project CT	098	Project CT Title	Project CT Status	Project CT Manager	Project CT Description	Project CT Location	Project CT Date	Project CT Notes	Project CT Contact
Project CU	099	Project CU Title	Project CU Status	Project CU Manager	Project CU Description	Project CU Location	Project CU Date	Project CU Notes	Project CU Contact
Project CV	100	Project CV Title	Project CV Status	Project CV Manager	Project CV Description	Project CV Location	Project CV Date	Project CV Notes	Project CV Contact
Project CW	101	Project CW Title	Project CW Status	Project CW Manager	Project CW Description	Project CW Location	Project CW Date	Project CW Notes	Project CW Contact
Project CX	102	Project CX Title	Project CX Status	Project CX Manager	Project CX Description	Project CX Location	Project CX Date	Project CX Notes	Project CX Contact
Project CY	103	Project CY Title	Project CY Status	Project CY Manager	Project CY Description	Project CY Location	Project CY Date	Project CY Notes	Project CY Contact
Project CZ	104	Project CZ Title	Project CZ Status	Project CZ Manager	Project CZ Description	Project CZ Location	Project CZ Date	Project CZ Notes	Project CZ Contact
Project DA	105	Project DA Title	Project DA Status	Project DA Manager	Project DA Description	Project DA Location	Project DA Date	Project DA Notes	Project DA Contact
Project DB	106	Project DB Title	Project DB Status	Project DB Manager	Project DB Description	Project DB Location	Project DB Date	Project DB Notes	Project DB Contact
Project DC	107	Project DC Title	Project DC Status	Project DC Manager	Project DC Description	Project DC Location	Project DC Date	Project DC Notes	Project DC Contact
Project DD	108	Project DD Title	Project DD Status	Project DD Manager	Project DD Description	Project DD Location	Project DD Date	Project DD Notes	Project DD Contact
Project DE	109	Project DE Title	Project DE Status	Project DE Manager	Project DE Description	Project DE Location	Project DE Date	Project DE Notes	Project DE Contact
Project DF	110	Project DF Title	Project DF Status	Project DF Manager	Project DF Description	Project DF Location	Project DF Date	Project DF Notes	Project DF Contact
Project DG	111	Project DG Title	Project DG Status	Project DG Manager	Project DG Description	Project DG Location	Project DG Date	Project DG Notes	Project DG Contact
Project DH	112	Project DH Title	Project DH Status	Project DH Manager	Project DH Description	Project DH Location	Project DH Date	Project DH Notes	Project DH Contact
Project DI	113	Project DI Title	Project DI Status	Project DI Manager	Project DI Description	Project DI Location	Project DI Date	Project DI Notes	Project DI Contact
Project DJ	114	Project DJ Title	Project DJ Status	Project DJ Manager	Project DJ Description	Project DJ Location	Project DJ Date	Project DJ Notes	Project DJ Contact
Project DK	115	Project DK Title	Project DK Status	Project DK Manager	Project DK Description	Project DK Location	Project DK Date	Project DK Notes	Project DK Contact
Project DL	116	Project DL Title	Project DL Status	Project DL Manager	Project DL Description	Project DL Location	Project DL Date	Project DL Notes	Project DL Contact
Project DM	117	Project DM Title	Project DM Status	Project DM Manager	Project DM Description	Project DM Location	Project DM Date	Project DM Notes	Project DM Contact
Project DN	118	Project DN Title	Project DN Status	Project DN Manager	Project DN Description	Project DN Location	Project DN Date	Project DN Notes	Project DN Contact
Project DO	119	Project DO Title	Project DO Status	Project DO Manager	Project DO Description	Project DO Location	Project DO Date	Project DO Notes	Project DO Contact
Project DP	120	Project DP Title	Project DP Status	Project DP Manager	Project DP Description	Project DP Location	Project DP Date	Project DP Notes	Project DP Contact
Project DQ	121	Project DQ Title	Project DQ Status	Project DQ Manager	Project DQ Description	Project DQ Location	Project DQ Date	Project DQ Notes	Project DQ Contact
Project DR	122	Project DR Title	Project DR Status	Project DR Manager	Project DR Description	Project DR Location	Project DR Date	Project DR Notes	Project DR Contact
Project DS	123	Project DS Title	Project DS Status	Project DS Manager	Project DS Description	Project DS Location	Project DS Date	Project DS Notes	Project DS Contact
Project DT	124	Project DT Title	Project DT Status	Project DT Manager	Project DT Description	Project DT Location	Project DT Date	Project DT Notes	Project DT Contact
Project DU	125	Project DU Title	Project DU Status	Project DU Manager	Project DU Description	Project DU Location	Project DU Date	Project DU Notes	Project DU Contact
Project DV	126	Project DV Title	Project DV Status	Project DV Manager	Project DV Description	Project DV Location	Project DV Date	Project DV Notes	Project DV Contact
Project DW	127	Project DW Title	Project DW Status	Project DW Manager	Project DW Description	Project DW Location	Project DW Date	Project DW Notes	Project DW Contact
Project DX	128	Project DX Title	Project DX Status	Project DX Manager	Project DX Description	Project DX Location	Project DX Date	Project DX Notes	Project DX Contact
Project DY	129	Project DY Title	Project DY Status	Project DY Manager	Project DY Description	Project DY Location	Project DY Date	Project DY Notes	Project DY Contact
Project DZ	130	Project DZ Title	Project DZ Status	Project DZ Manager	Project DZ Description	Project DZ Location	Project DZ Date	Project DZ Notes	Project DZ Contact
Project EA	131	Project EA Title	Project EA Status	Project EA Manager	Project EA Description	Project EA Location	Project EA Date	Project EA Notes	Project EA Contact
Project EB	132	Project EB Title	Project EB Status	Project EB Manager	Project EB Description	Project EB Location	Project EB Date	Project EB Notes	Project EB Contact
Project EC	133	Project EC Title	Project EC Status	Project EC Manager	Project EC Description	Project EC Location	Project EC Date	Project EC Notes	Project EC Contact
Project ED	134	Project ED Title	Project ED Status	Project ED Manager	Project ED Description	Project ED Location	Project ED Date	Project ED Notes	Project ED Contact
Project EE	135	Project EE Title	Project EE Status	Project EE Manager	Project EE Description	Project EE Location	Project EE Date	Project EE Notes	Project EE Contact
Project EF	136	Project EF Title	Project EF Status	Project EF Manager	Project EF Description	Project EF Location	Project EF Date	Project EF Notes	Project EF Contact
Project EG	137	Project EG Title	Project EG Status	Project EG Manager	Project EG Description	Project EG Location	Project EG Date	Project EG Notes	Project EG Contact
Project EH	138	Project EH Title	Project EH Status	Project EH Manager	Project EH Description	Project EH Location	Project EH Date	Project EH Notes	Project EH Contact
Project EI	139	Project EI Title	Project EI Status	Project EI Manager	Project EI Description	Project EI Location	Project EI Date	Project EI Notes	Project EI Contact
Project EJ	140	Project EJ Title	Project EJ Status	Project EJ Manager	Project EJ Description	Project EJ Location	Project EJ Date	Project EJ Notes	Project EJ Contact
Project EK	141	Project EK Title	Project EK Status	Project EK Manager	Project EK Description	Project EK Location	Project EK Date	Project EK Notes	Project EK Contact
Project EL	142	Project EL Title	Project EL Status	Project EL Manager	Project EL Description	Project EL Location	Project EL Date	Project EL Notes	Project EL Contact
Project EM	143	Project EM Title	Project EM Status	Project EM Manager	Project EM Description	Project EM Location	Project EM Date	Project EM Notes	Project EM Contact
Project EN	144	Project EN Title	Project EN Status	Project EN Manager	Project EN Description	Project EN Location	Project EN Date	Project EN Notes	Project EN Contact
Project EO	145	Project EO Title	Project EO Status	Project EO Manager	Project EO Description	Project EO Location	Project EO Date	Project EO Notes	Project EO Contact
Project EP	146	Project EP Title	Project EP Status	Project EP Manager	Project EP Description	Project EP Location	Project EP Date	Project EP Notes	Project EP Contact
Project EQ	147	Project EQ Title	Project EQ Status	Project EQ Manager	Project EQ Description	Project EQ Location	Project EQ Date	Project EQ Notes	Project EQ Contact
Project ER	148	Project ER Title	Project ER Status	Project ER Manager	Project ER				

A		B		C		D		E		F		G		H		I		J		K		L		M		N		O		P		Q		R		S		T		U		V		W		X		Y		Z		AA		AB		AC		AD		AE		AF		AG		AH		AI		AJ		AK		AL		AM		AN		AO		AP		AQ		AR		AS		AT		AU		AV		AW		AX		AY		AZ		BA		BB		BC		BD		BE		BF		BG		BH		BI		BJ		BK		BL		BM		BN		BO		BP		BQ		BR		BS		BT		BU		BV		BW		BX		BY		BZ		CA		CB		CC		CD		CE		CF		CG		CH		CI		CJ		CK		CL		CM		CN		CO		CP		CQ		CR		CS		CT		CU		CV		CW		CX		CY		CZ		DA		DB		DC		DD		DE		DF		DG		DH		DI		DJ		DK		DL		DM		DN		DO		DP		DQ		DR		DS		DT		DU		DV		DW		DX		DY		DZ		EA		EB		EC		ED		EE		EF		EG		EH		EI		EJ		EK		EL		EM		EN		EO		EP		EQ		ER		ES		ET		EU		EV		EW		EX		EY		EZ		FA		FB		FC		FD		FE		FF		FG		FH		FI		FJ		FK		FL		FM		FN		FO		FP		FQ		FR		FS		FT		FU		FV		FW		FX		FY		FZ		GA		GB		GC		GD		GE		GF		GG		GH		GI		GJ		GK		GL		GM		GN		GO		GP		GQ		GR		GS		GT		GU		GV		GW		GX		GY		GZ		HA		HB		HC		HD		HE		HF		HG		HH		HI		HJ		HK		HL		HM		HN		HO		HP		HQ		HR		HS		HT		HU		HV		HW		HX		HY		HZ		IA		IB		IC		ID		IE		IF		IG		IH		II		IJ		IK		IL		IM		IN		IO		IP		IQ		IR		IS		IT		IU		IV		IW		IX		IY		IZ		JA		JB		JC		JD		JE		JF		JG		JH		JI		JJ		JK		JL		JM		JN		JO		JP		JQ		JR		JS		JT		JU		JV		JW		JX		JY		JZ		KA		KB		KC		KD		KE		KF		KG		KH		KI		KJ		KL		KM		KN		KO		KP		KQ		KR		KS		KT		KU		KV		KW		KX		KY		KZ		LA		LB		LC		LD		LE		LF		LG		LH		LI		LJ		LK		LM		LN		LO		LP		LQ		LR		LS		LT		LU		LV		LW		LX		LY		LZ		MA		MB		MC		MD		ME		MF		MG		MH		MI		MJ		MK		ML		MM		MN		MO		MP		MQ		MR		MS		MT		MU		MV		MW		MX		MY		MZ		NA		NB		NC		ND		NE		NF		NG		NH		NI		NJ		NK		NL		NM		NN		NO		NP		NQ		NR		NS		NT		NU		NV		NW		NX		NY		NZ		OA		OB		OC		OD		OE		OF		OG		OH		OI		OJ		OK		OL		OM		ON		OO		OP		OQ		OR		OS		OT		OU		OV		OW		OX		OY		OZ		PA		PB		PC		PD		PE		PF		PG		PH		PI		PJ		PK		PL		PM		PN		PO		PP		PQ		PR		PS		PT		PU		PV		PW		PX		PY		PZ		QA		QB		QC		QD		QE		QF		QG		QH		QI		QJ		QK		QL		QM		QN		QO		QP		QR		QS		QT		QU		QV		QW		QX		QY		QZ		RA		RB		RC		RD		RE		RF		RG		RH		RI		RJ		RK		RL		RM		RN		RO		RP		RQ		RR		RS		RT		RU		RV		RW		RX		RY		RZ		SA		SB		SC		SD		SE		SF		SG		SH		SI		SJ		SK		SL		SM		SN		SO		SP		SQ		SR		SS	
A printed circuit board having a first layer of conductive material, a second layer of conductive material, and a third layer of conductive material, the first layer of conductive material being disposed on a first substrate, the second layer of conductive material being disposed on the first substrate, and the third layer of conductive material being disposed on the second layer of conductive material.																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																																											
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Bureau of Land Management  
202 234-0529

On 11 Oct 21, 2024 at 1:53 PM, the user Briza-Blanca van@blm.gov wrote:  
Hi Chad, Thanks for the response. We are not aware of any policy that would be going on. I would like to know if anything is in the air or if there are any other policies that we should be aware of.

We look forward to working with you to clear this up. Thanks! Briza

Briza-Blanca  
Frog and Owl  
202 234-0529  
Bureau of Land Management  
202 234-0529

On 11 Oct 21, 2024 at 1:53 PM, Young, Briza-Blanca van@blm.gov wrote:  
Hi Briza,

We are not aware of any policy that would be going on. I would like to know if anything is in the air or if there are any other policies that we should be aware of.

Thanks for your patience and I look forward to hearing from you if there are any other questions.

Chad

Chad Dyer  
Comment: Briza-Blanca  
We have not seen any policy that would be going on. I would like to know if anything is in the air or if there are any other policies that we should be aware of.

DTS #	Name	Date Rec'd by WO410
BLM0009617	Donation of Private Lands to the Bureau of Land Management (BLM) for Addition to the Sabinoso Wilderness Area	12/29/2016
BLM0009637	Response to SO 3342 on Tribal Partnerships & Cooperative Management	12/20/2016
BLM0006244	Proposed San Joaquin Wild and Scenic River Designation	4/14/2016
BLMR001342	Call for Nominations for GSENMAC	11/22/2016
BLMR006696	Awaiting signatures from other agencies NATIONAL TRAILS SYSTEM MEMORANDUM OF UNDERSTANDING	11/28/2016
BLM0008813	WSR 50th Anniversary MOU	11/29/2016
BLM0009609	Write in campaign: oppose potential Bears Ears Monument	12/15/2016
BLM0009630	Supports expansion of Cascade Siskiyou National Monument	12/20/2016
BLM0009617	Donation of Private Lands to the Bureau of Land Management (BLM) for Addition to the Sabinoso Wilderness Area	12/29/2016
BLM0009667	Bears Ears	12/30/2016
BLM0009669	Bears Ears	12/30/2016
BLM0009670	Bears Ears and Gold Butte	12/30/2016
BLM0009671	Bears Ears	12/30/2016
BLM0009672	California Costal National Monument	12/30/2016
BLM0009674	Bears Ears	12/30/2016
BLM0009679	Bears Ears	12/30/2016
BLM0009682	Bears Ears	12/30/2016
BLM0009683	Gold Butte National Monument proposal	12/30/2016
BLM0009709	FY 2017 National Monument & National Conservation Area Program Manager's Reports IM	1/5/2017
BLM0009814	2017 Interagency National Wilderness Leadership Training	1/26/2017
BLM0009796	Bears Ears National Monument	1/25/2017
BLM0009783	Bears Ears thank you	1/23/2017